



75<sup>TH</sup>  
Anniversary

40<sup>YEARS OF</sup> IEEE Hyderabad Section



Microwaves, Antennas and Propagation Conference - 2024

# IEEE MICROWAVES, ANTENNAS AND PROPAGATION CONFERENCE

December 09-13, 2024

Hyderabad International Convention Centre, Hyderabad

## SPONSORSHIP BROCHURE

Organized By:  
MTT-S/ AP-S/ EMC-S Joint Chapter, Hyderabad

Please visit [www.ieeemapcon.org](http://www.ieeemapcon.org) for further details.

# INVITATION TO PARTICIPATE IN MAPCON 2024

Dear Colleagues,

IEEE Microwaves, Antennas and Propagation Conference, MAPCON-2024 will be held from December 9-13, 2024 at The Novotel Hitex Convention Centre, Hitec City, Hyderabad, India. This is the third edition of the MAPCON co-sponsored by IEEE MTT-S and IEE AP-S. The conference will be held in in-person (physical) mode. This Conference provides an excellent international platform for sharing of state-of-the-art research/technologies in the field of microwaves and antennas, wherein many national/international eminent personalities will share their vision, expertise and knowledge. MAPCON-2024 will include a wide range of technical sessions, invited talks, workshops, tutorials, special sessions, student design competitions, industry sessions, exhibits, professional meetings, tours and networking events. It will also hold Ph.D. initiative activities, Young Professional, Women-In Engineering, SIGHT and start-up initiative activities.

The first edition of MAPCON was organized in Bangalore, India during Dec 12-15, 2022. It was grand success with 600+ papers and 800 plus delegates participating from various Government, Private and Academic organizations of various countries. The conference has grown to 900+ delegates in 2023 in Ahmedabad and more than 60 industry sponsors. In 2024 we expect the delegate numbers to exceed 1000 and are planning for a grand exhibition which would feature some key product launches/introductions from major industries in RF/Microwave and antenna areas.

The key focus of this conference will be on expert talks by internationally renowned professionals, workshops/tutorials by eminent speakers, oral/poster paper presentations by researchers and exhibition by global industries. MAPCON 2024 is a right opportunity to showcase state of the art technologies, measurement facilities and modelling tools available in Antenna/Microwave & RF industries.

This is a 5 days long conference where more than 1000 participants from various countries (USA, Europe, UK, Australia, Japan, Taiwan, South Korea and other Asian countries), Indian research organizations (ISRO, BARC, DRDO, DAE etc.), Indian academic institutes, Start-ups, Industries, and Students are expected to attend this conference. This international event offers an outstanding opportunity to sponsoring and exhibiting partners to showcase their company's products/services and applications to a vibrant and engaged audience and provides an ideal platform to reach hundreds of key decision-makers.

On behalf of the executive committee of MAPCON 2024, it is our great pleasure to invite you to be a valued sponsor at the event. MAPCON offers multiple levels of sponsorship and exhibitor opportunities to promote your organization to this influential audience. We would like you to sponsor this event as a Platinum/ Gold/ Silver/ Bronze sponsor. The details for the same are contained in the attached document. To foster innovation MAPCON 2024 is also imparting special discounts to Start-ups registered with DPIIT.

Looking forward to seeing you in the MAPCON 2024, at Hyderabad.

**Yogesh Kumar Verma**  
RCI, DRDO, Hyderabad

**Sandeep Chaturvedi**  
GAETEC, Hyderabad



# COMMITTEE DETAILS

## Chief Patrons



**Sameer V Kamath**  
Secretary DDR&D &  
Chairman, DRDO



**S. Somnath**  
Secretary DoS &  
Chairman, ISRO

## Patrons



**B.K. Das**  
DS & DG-ECS, DRDO



**Suma Varughese**  
DS & DG-Med, CoS &  
CS (MCC), DRDO



**U. Raja Babu**  
DS & DG-MSS, DRDO



## MAPCON 2024 Advisory Council



**G. Viswam**  
Director, LRDE



**Rajalakshmi Menon**  
Director, CABS, Bangalore



**M. Sankaran**  
Director, URSC, Bangalore



**Nilesh Desai**  
Director, SAC, Ahmedabad



**Jagannath Nayak**  
Director, CHES, Hyderabad



**Meena Mishra**  
Director, SSPL



**L.C. Mangal**  
Director, DEAL



**P. Hanumantha Rao**  
Director General, SAMEER

## MAPCON 2024 Executive Committee



**Goutam Chattopadhyay**  
NASA JPL, USA



**Yahia M. Antar**  
Royal Military College,  
Canada



**Shibban K. Koul**  
IIT Delhi, India



**Debatosh Guha**  
University of Calcutta India



**Rajeev Jyoti**  
IN-SPACE, ISRO,  
Ahmedabad, India



**Usha P. Verma**  
ASL DRDO, Hyderabad,  
India



**K.J. Vinay**  
IISc Bengaluru, India



**Puneet K. Mishra**  
URSC ISRO, Bangalore,  
India



**Chinmoya Saha**  
IIST Trivandrum, India



**Jaleel M. Akhtar**  
IIT Kanpur



## Organizing Committee

### General Co-Chairs



**Yogesh Kumar Verma**  
RCI, DRDO, Hyderabad



**Sandeep Kumar Chaturvedi**  
GAETEC, Hyderabad

### TPC Co-chairs



**K.P. Ray**  
DIAT, Pune



**Shobha Sundar Ram**  
IIIT Delhi

### Finance Co-chairs



**Prashant Kumar Mishra**  
RCI, DRDO, Hyderabad



**Nookala Srinivas Rao**  
MECS, Hyderabad

### Sponsorship Co-chairs



**Sandeep Satav**  
RCI, DRDO, Hyderabad



**Puneet Mishra**  
URSC, Bangalore

### Industry Engagement Committee



**M.V. Reddy**  
AMPL, Hyderabad



**Sunil Motwani**  
Mathworks, Hyderabad



**Shubhomoy Chakravarti**  
ABP News



**Debabani Chaudhari**  
Intel labs, USA



**Ashutosh Baheti**  
Paras Anti-drone Technol-  
ogies, Bangalore

### Exhibition Committee



**Rakesh Kumar Singh**  
RCI, Hyderabad



**Dovari Nagaraju**  
RCI, Hyderabad



**Amit Prabhat Singh**  
SMRC, GAETEC,  
Hyderabad

## Industry Microapps



**Sai Krishna Puranam**  
Dassault Systems CST



**Deepti Das Krishna**  
CUSAT, Kochi

## Gol liaison



**Manish Kumar Hooda**  
MeitY, New Delhi



**Subhash Chander**  
SSPL, DRDO, Delhi

## Publicity Committee



**Akash Bansal**  
Loughborough  
University, UK



**BS Manoj**  
IIST,  
Thriuvananthapuram



**Chinmoy Saha**  
IIST,  
Thriuvananthapuram



**Erin M Kiley**  
Massachusetts  
College of Liberal  
Arts, USA



**Yang Yang**  
University of  
Technology Sydney,  
Australia

## Startup Initiative



**Anindya Saha**  
Tejas Networks, Bangalore



**Srikanth Reddy**  
Doppler Electronics, Hyderabad

## Publications Committee



**Dr. Chandrakanta Kumar**  
URSC, Bangalore



**Dr. Sukomal Dey**  
IIT Pallakad

## Workshop Committee



**Raghavendra  
Chaudhary**  
IIT Kanpur



**Madhur Dev  
Upadhyay**  
Shiv Nader University,  
Noida



**Debdeep Sarkar**  
IISc Bangalore



**Karun Rawat**  
IIT Roorkee

## Tutorials & FDP Committee



**Mahesh Abegaonkar**  
 IIT Delhi



**Manoj Singh Parihar**  
 IIITDM Jabalpur



**Anamiya Bhattacharya**  
 SAC Ahmedabad



**G. Arun Kumar**  
 NIT Warangal



**Manjunatha H.V.**  
 Cadence Design Systems-  
 AWR, Bangalore



**Shashank Kulkarni**  
 Mathworks, Hyderabad

## Young Professionals Committee



**Amit Kumar Singh**  
 IIT Patna



**Gopi Ram**  
 NIT Warangal



**Arjuna Muduli**  
 JSPM University, Pune



**Ashish Jindal**  
 SSPL - DRDO, Delhi



**Christy Prasad Jones**  
 QIS College of Engg. &  
 Tech. - Ongole

## Special Sessions Committee



**Ashutosh Kedar**  
 LRDE - DRDO, Bangalore



**Umakant Goyal**  
 SSPL- DRDO, Delhi



**M. Naresh**  
 MEC, Hyderabad



**Rakesh Kichouliya**  
 RCI - DRDO, Hyderabad

## Women in Engineering



**Meena Mishra**  
 SSPL Delhi, India



**Hema Singh**  
 NAL, Bangalore, India



**Meenakshi Rawat**  
 IIT Roorkee, India



**Charloette Blair**  
 Ansys Inc., USA



**Kim Eilert**  
 BAE Systems Inc., USA



**Sherry HESS**  
 Cadence Inc.,  
 USA



**Jasmine Grosinger**  
 Graz University of  
 Technology, Austria



**Amelie Hagelauer**  
 Technical University  
 Munich, Germany



**Kanthi Sudha**  
 VNR VJIEI,  
 Hyderabad, India



**Bharathi Anantha**  
 Osmania University,  
 Hyderabad, India

## SIGHT



**Ajay K. Poddar**  
 Synergy Microwave Inc.  
 USA



**M.A. Jabbar**  
 Vardhaman College of  
 Engineering, Hyderabad, India



**Anisha Apte**  
 Synergy Microwave  
 Inc, USA



**S. Ram Mohan**  
 NIAR, Hyderabad

## Phd. Initiative



**Jolly Dhar**  
 SAC-ISRO, Ahmedabad



**Somak Bhattacharya**  
 IIT - BHU, Varanasi



**Rakesh Sinha**  
 NIT Rourkela



**Debapratim Ghosh**  
 IIT Bhubaneswar



**Mridula Gupta**  
 Delhi University, South  
 Campus, Delhi

## M.Tech Initiative



**Saptarshi Ghosh**  
 IIT Indore



**SS Karthikeyan**  
 NIT Trichy

## B.Tech. Initiative



**Arvind Kumar**  
 VNIT Nagpur



**Shubhankar Majumdar**  
 NIT Meghalay



**Hemant Kumar**  
 NIT Trichy

## Student Design Contest



**Harish Dixit**  
 BITS Pilani, Hyderabad



**Dinesh Yadav**  
 Manipal University, Jaipur



**Sanjeev Kumar Mishra**  
 IIIT Bhubaneswar



**Akhilesh Verma**  
 Aqila Technologies, Noida



## STEM Outreach



**Jawad Y. Siddiqui**  
 Royal Military College,  
 Canada



**G.S. Mani**  
 Former Dean & Director,  
 DIAT, Pune



**Divya Nalla**  
 NMREC, Hyderabad

## Website, IT and Social Media Committee



**Vinit Kumar Gunjan**  
 CMRIT Hyderabad



**Sandeep Dogiparthi**  
 Feuji Inc, Hyderabad



**Suneel Varma**  
 AMPL, Hyderabad

## Life Member Committee



**M. Lakshminarayana**  
 Unistring Tech. Solutions,  
 Hyderabad



**B.L. Deekshitulu**  
 Former Director, NRSC-ISRO,  
 Hyderabad



**K.M.M. Rao**  
 Former Deputy Director,  
 NRSC-ISRO, Hyderabad

## Inter Society Committee



**Mousmi Ajay Chaurasia**  
 MJCET, Hyderabad



**Kavitha**  
 JNTU, Hyderabad



**Y. Padamasai**  
 VNR VJIET, Hyderabad



**Umashanker Sahu**  
 NITTR, Hyderabad



**Dr. Vedula VSSS Chakravarthy**  
 Raghu Engineering  
 College, Visakhapatnam

## Local Advisory Committee



**Y. Vijayalatha**  
 Chair, IEEE Hyderabad  
 Section



**Amit Kumar**  
 Chair, Conference  
 Committee, IEEE  
 Hyderabad Section



**V. Jayprakashan**  
 Treasurer,  
 IEEE Hyderabad Section



**M. Lakshminarayana**  
 Unistring Tech.  
 Solutions, Hyderabad



**D. R. Jahagirdar**  
 RCI, DRDO,  
 Hyderabad

## PREMIER SPONSORSHIP OPPORTUNITIES

You can become a premier sponsor, singular sponsor, or an exhibitor of MAPCON 2024. Premier sponsors - Platinum, Gold, Silver & Bronze sponsors enjoy exclusive benefits, including wide acknowledgement and priority to select certain sponsorship items.

Premier Sponsorship	Amount (INR)	Amount (USD)
Platinum	INR 20,00,000	USD 24,500
Gold	INR 15,00,000	USD 20,000
Silver	INR 10,00,000	USD 15,000
Bronze	INR 8,00,000	USD 10,000

## PREMIER SPONSORSHIP DELIVERABLES

*Details of premier sponsorship and inclusions are as below:*

Benefits	Platinum	Gold	Silver	Bronze
Complimentary registration for company employees/ delegates	12	8	6	4
Endorsement as a Prime Sponsor (as per the category)	✓	✓	✓	✓
Acknowledgement on the sponsor panel	✓	✓	✓	✓
Acknowledgement on the conference backdrop	✓	✓	✓	✓
Acknowledgement on Conference website	✓ (Hyperlinked to company website)	✓ (Hyperlinked to company website)	✓	✓
Complimentary insertion in Delegate kit. Design must be approved by OC.	✓ (One A4 size flyers)	✓ (One A5 size flyers)		
Exhibition booth size	9m x 6m	6m x 6m	6m x 3m	3m x 3m
Banquet Presentation slot (20 minutes)	✓			
Workshop Slot (1 Hour)	✓			
Acknowledgement during Inaugural, Awards, Banquet and Valedictory functions	✓	✓	Awards and Valedictory only	Awards and Valedictory only



## OTHER SPONSORSHIP OPPORTUNITIES

Other Sponsorship Opportunities	Amount (INR)	Slot
Presentation slot (15 minutes)	INR 2,50,000	Only for Premier Sponsors

(limited numbers - On first come first serve basis)

Advertisement in Program book		
Back Cover Page	INR 5,00,000	Exclusive
Inside the Back-Cover Page	INR 4,00,000	Exclusive
Inside the Front-Cover Page	INR 4,00,000	Exclusive
Half page (run of the book)	INR 3,00,000	Multiple
Banner on the conference website	INR 5,00,000	Multiple
Lanyards (company logo along with conference and organisers' logo)	INR 8,00,000	Exclusive
Delegate bags	INR 15,00,000	Only for Premier Sponsors
Conference notebook and pens	INR 5,00,000	Exclusive
Mobile App Sponsor	INR 3,50,000	Exclusive
Internet sponsor	INR 10,00,000	Exclusive
Hydration sponsor (Logo on the Water dispenser)	INR 3,50,000	Exclusive

Advertisement options at the venue		
LED outside HICC entrance per LED per day (1040 Pixels Width & 624 Pixels Height LED wall)	INR 80,000	One LED per day. Only 2 LED options available
LED inside HICC entrance LEFT side per day (Pixel Ratio: 1080 x 1920 )	INR 50,000	Only one LED available.
HICC Main lobby Pillar Branding 2 sides digital branding per day / per pillar. Pillar each side size: 5 ft width x 10 ft height. Pixel ratio: 5760 x 3240	INR 50,000	Only one pillar with two sides available.

**\*Kindly note that the above charges for advertisement options at the venue are for per day.**

## EXHIBITION OPPORTUNITIES

Exhibition Booth Size	Amount (INR)
3m x 2m	INR 5,00,000
2m x 2m	INR 3,50,000

**\*Each 3m x 2m and 2m x 2m space will come with two complimentary exhibitor passes which can be utilised for the representatives to man the booths, onsite.**

**\*2x2mtr stall are only meant for startups with DPIIT registration and academic institutions.**

**NOTE: All the above rates are exclusive of applicable taxes.**

## HOW TO APPLY

Decisions regarding the admission of exhibitors, exhibits and the allocation of space will be conveyed by the Congress Secretariat. While sponsorship contracts will be concluded by the date of payment with exhibitors giving their preferred booth number(s), the final allocation of exhibition space will be made later.

**For further details on the opportunities available please contact:**

**Yogesh Kumar Verma & Sandeep Chaturvedi**  
General Co-Chairs, MAPCON 2024  
[sponsors.mapcon2024@ieeemapcon.org](mailto:sponsors.mapcon2024@ieeemapcon.org)

## BANK DETAILS

Account Name : ELISYAN India Pvt. Ltd.  
Account No. : 50200038929996  
IFSC Code : HDFC0003871  
Bank Name : HDFC Bank Ltd  
Address : SCO-39, Sector - 56, Gurgaon - 122 002  
Swift Address No : HDFCINBB

## ALLOCATION OF EXHIBITION SPACE

Premier Sponsors registered before 30th June 2024 have the priorities to choose their preferred spaces. Priority of the allocation of exhibition space with the Premier Sponsors will be offered to the highest bidder. Other Sponsors will be treated on a "first-come, first-served" basis.

## EXHIBITOR MANUAL

A technical Manual outlining all technical aspects of the exhibition will be circulated one month before the Conference. It will include the following:

- Technical details about the Venue
- Final exhibition details and information
- Contractor details
- Services available to exhibitors and order forms

## TERMS AND CONDITIONS

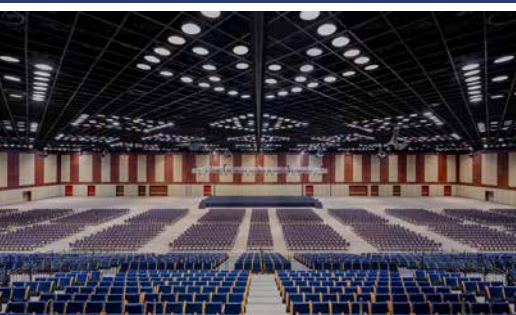
1. The number of representatives of sponsors at the congress venue will be limited depending upon the extent and area of sponsorship at the discretion of the Organizing Committee.
2. All the sponsors should register names of their representatives with the Organizing Committee one month before the start of congress and all such persons will be required to wear the ID badges provided.
3. Stalls will be allocated on first come, first served basis with priority given to the premier sponsors.
4. The Organizing Committee reserves the right to rearrange the floor plan or any part thereof at any time. An official receipt towards provisional booking amount shall be issued within three weeks of receipt of payment.
5. The Organizing Committee reserves the right to change the venue and date of exhibition in case of unavoidable circumstances.
6. The Organizing Committee shall in no way be responsible for any tax liability incurred for any sale/booking transaction undertaken by the exhibitors.
7. No loud music/ videos will be allowed in the exhibition area in the booths, which could be a disturbance for others.
8. Transferring any category of sponsorship or the booths/ exhibit space to another company is strictly not allowed.

## FORCE MAJEURE

1. Neither party shall be liable to the other for any loss or damage occasioned by or arising out of Act of God (such as epidemics, floods, volcanic eruption, earthquakes or other convulsions of nature and other acts) and other unprecedented events such as general strike, invasions, hostilities, war, rioting or similar situations which prevent performance of the contract and which could not have been foreseen or avoided by a prudent person/ action.
2. No sale in cash or credit of products and services shall be allowed at the stalls. However, booking could be done for delivery at a later date. The Organizing Committee shall in no way be responsible for any tax liability incurred for any sale / booking undertaken by the exhibitors.

## THE VENUE

Hyderabad International Convention Centre (HICC) is a purpose-built, state-of-the-art convention facility, the first-of-its-kind and the best standalone convention centre in South Asia. It features an internal hall measuring 6,480 square meters that can be partitioned into six smaller halls. There are 21 small meeting rooms to accommodate 50 - 180 pax in different seating styles. Adjacent to the convention centre is Novotel Hyderabad Convention Centre with residential rooms, which makes it convenient for the conference organisers and delegates to stay.



# EXHIBITION LAYOUT



Conference Secretariat:

IEEE Hyderabad Section,  
MTT-S/AP-S/EMC-S Joint Chapter  
No: 644-645, Al-Karim Trade Center,  
Ranigunj, Secunderabad - 500 003,  
Telangana. India.

Conference Manager:



ELISYAN<sup>®</sup>  
Elisyan India Pvt. Ltd.  
(www.elisyan.in)

E: mapcon2024@ieeemapcon.org

P: +91 973 993 7911

Please visit [www.ieeemapcon.org](http://www.ieeemapcon.org) for further details.